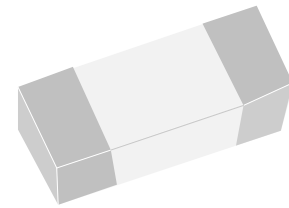


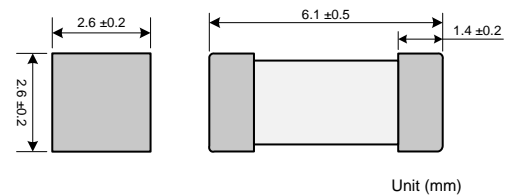
**Fast Acting SMD Fuses 2410BC 125VAC/DC Series**
**Descriptions**

Chip Fuse devices are set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

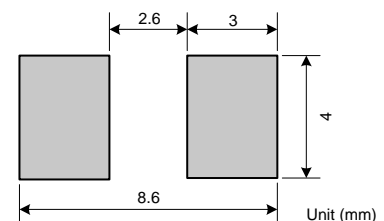
2410BC SMD fuses for the small size and good electrical performance, reliability and quality.


**Top View (2410BC)**

Electrical Characteristics		
Rated Current	1.0In	2.0In
2A~15A	4 hour minimum	5 sec maximum

**Product Dimensions**

**Features**

- Designed to UL 248-14
- Compatible with reflow and wave soldering
- One time positive disconnect
- RoHS compliant

**Recommended land pattern**

**Electrical information (Tamb=25°C)**

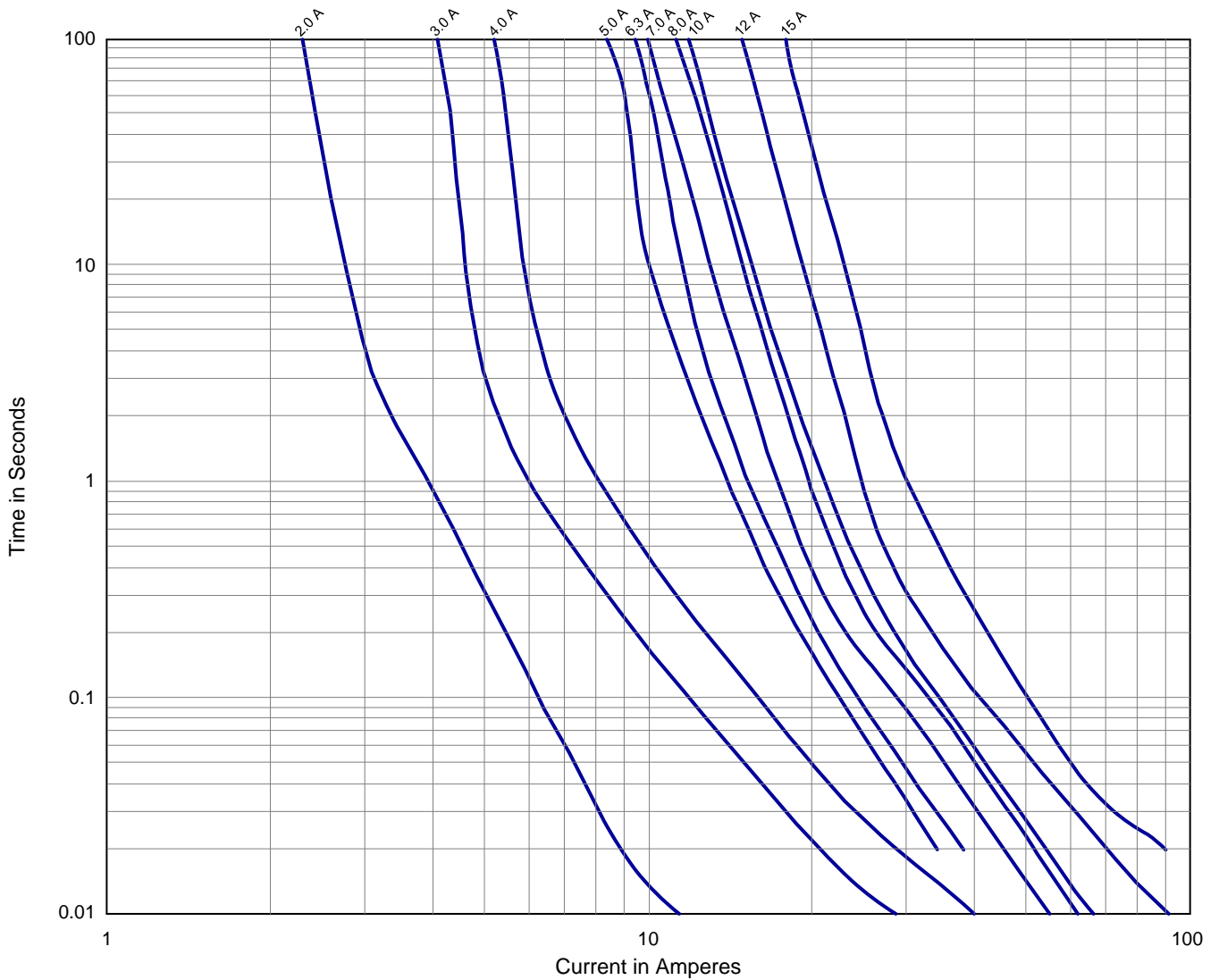
Part number	Rated Voltage	Rated Current	Breaking Capacity * (A)		Typical Cold Resistance *	Typical Voltage Drop	Typical Pre-arcing I <sup>2</sup> t *
	AC/DC (V)	(A)	125V AC	125V DC	(mΩ)	(mV)	(A <sup>2</sup> Sec)
2410BC125-0200	125	2.0	50	300	40	150	0.8
2410BC125-0300	125	3.0	50	300	26	130	1.95
2410BC125-0400	125	4.0	50	300	19	110	4
2410BC125-0500	125	5.0	50	300	14	100	7.5
2410BC125-0630	125	6.3	63	300	9.45	95	13
2410BC125-0700	125	7.0	70	300	8.35	90	16
2410BC125-0800	125	8.0	80	300	6.35	85	20
2410BC125-1000	125	10.0	100	300	5.25	80	35
2410BC125-1200	125	12.0	50	300	4.30	75	40
2410BC125-1500	125	15.0	50	300	3.15	67	55

\* AC Interrupting Rating (measured at designated voltage, 100% power factor); DC Interrupting Rating (measured at designated voltage, time constant of less than 50 microseconds, battery source)

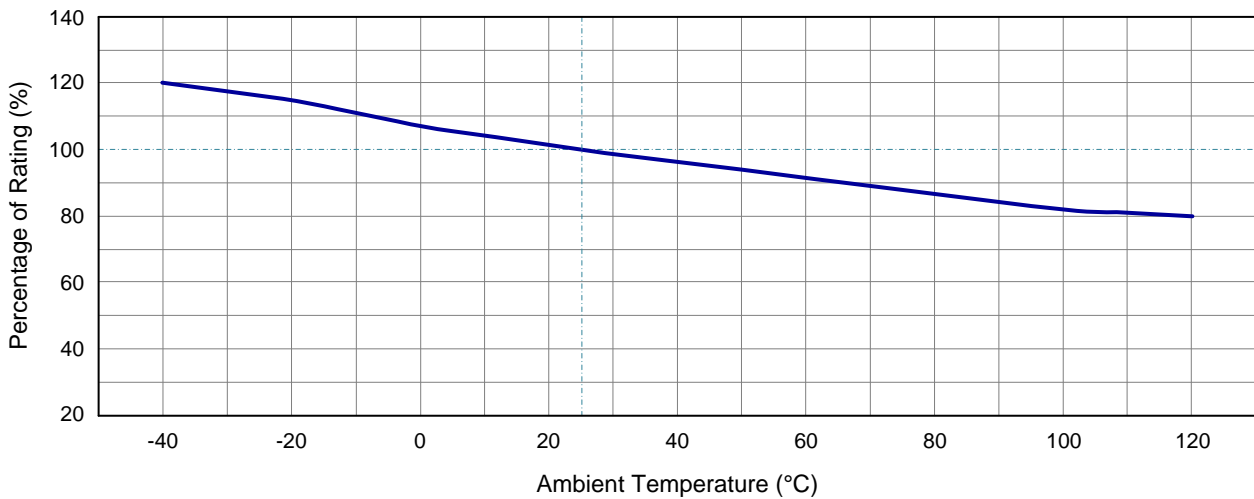
\* DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 °C

\* Typical Pre-arcing I<sup>2</sup>t are measured at 10In Current

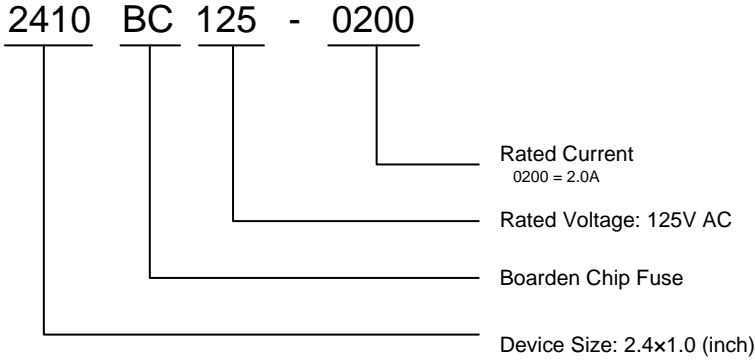
**Time-Current Curves**



**Temperature Derating Curve**



**Part Numbering System**

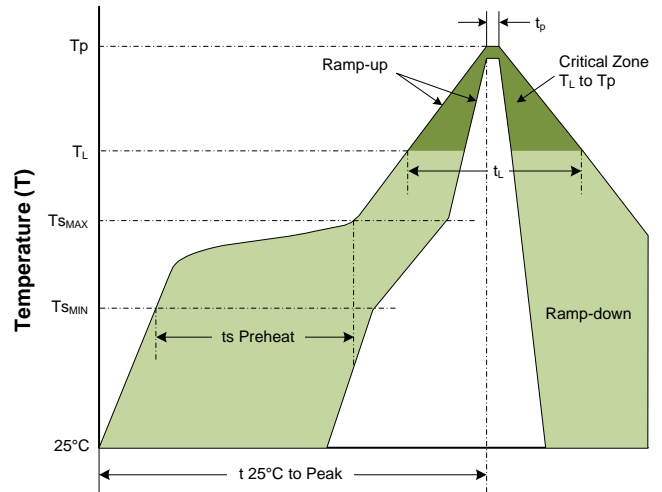


**Order Information**

Device	Quantity	Reel Size
2410BC125 Series	1000 pcs	7 Inch (178.0mm)

**Soldering Parameters**

Profile Feature	Lead-Free Assembly
Average Ramp-up Rate ( $T_{S_{MAX}}$ to $T_p$ ) Average Ramp-down Rate ( $T_p$ to $T_L$ )	3°C/second max. 6°C/second max.
<b>Preheat</b> • Temperature Min ( $T_{S_{MIN}}$ ) • Temperature Max ( $T_{S_{MAX}}$ ) • Time ( $t_s$ Preheat)	150°C 200°C 60-180 seconds
<b>Time maintained above:</b> • Temperature ( $T_L$ ) • Time ( $t_L$ )	217°C 60-150 seconds
<b>Peak/Classification Temperature</b> • Temperature ( $T_p$ )	260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual Peak</b> Time ( $t_p$ )	20-40 seconds
<b>Time 25°C to peak Temperature</b>	8 minutes max
<b>Do not exceed</b>	280 °C



© 2017 Boarden Electronics Ltd.  
Specifications are subject to change without notice.

Website: [www.boarden.com.cn](http://www.boarden.com.cn)  
Tel: 86-21-61401058  
Fax: 86-21-61730538